



Material Content Data Sheet



Sales Product Name		SAF-C165-LF 3V HA		Issued		29. August 2013		
MA#		MA000098935						
Package		PG-TQFP-100-1		Weight*		702.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.727	1.95	1.95	19540	19540
leadframe	non noble metal	nickel	7440-02-0	77.443	11.02		110236	
	non noble metal	iron	7439-89-6	106.945	15.22	26.24	152231	262467
wire	noble metal	gold	7440-57-5	6.159	0.88	0.88	8767	8767
encapsulation	organic material	carbon black	1333-86-4	1.449	0.21		2062	
	plastics	epoxy resin	-	61.327	8.73		87296	
	inorganic material	silicondioxide	60676-86-0	420.111	59.81	68.75	598007	687365
leadfinish	non noble metal	tin	7440-31-5	6.211	0.88	0.88	8842	8842
plating	noble metal	silver	7440-22-4	6.180	0.88	0.88	8797	8797
glue	plastics	acrylic resin	-	0.593	0.08		844	
	noble metal	silver	7440-22-4	2.373	0.34	0.42	3378	4222
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com